

ABSTRACT

A polishing apparatus according to the present invention has a polishing surface (101), a top ring (1) for holding a semiconductor wafer (W), and a top ring shaft (11) for pressing the top ring (1) against the polishing
5 surface (101). The top ring (1) has a retainer ring (3) for holding a peripheral portion of the semiconductor wafer (W), a housing (2) substantially in a form of a disk which is connected to the top ring shaft (11), a sliding contact joint (4, 5, 6, 2b) interconnecting the retainer ring (3) and the housing (2) in a state such that the retainer ring (3) and the housing (2) are brought
10 into sliding contact with each other.